

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
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ATSUSHI TOMOHIRO	05/12/2015
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PROPERTY NUMBERS Total: 1	
Property Type	Number
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DATE SIGNED:	05/13/2015
Total Attachments: 2 source=Assignment#page1.tif source=Assignment#page2.tif	

ASSIGNMENT BY INVENTOR

This Assignment is by Atsushi Tomohiro, having a mailing address of c/o Micron Akita, Inc., 89-2, Yamada, Yuwaishida, Akita-shi, Akita, 010-1222 Japan (the "Assignor").

The Assignor invented one or more certain inventions (the "Invention(s)") described in (1) an application for patent naming the Assignor as inventor, and filed with the Japan Patent Office on May 14, 2014 as Japan Patent Application No. 2014-100176; and (2) an application for patent naming the Assignor as inventor, titled SEMICONDUCTOR DEVICE INCLUDING SEMICONDUCTOR CHIP COVERED WITH SEALING RESIN, and filed with the U.S. Patent and Trademark Office on _____ as U.S. Application No. _____ (the "Application"). The Assignor authorizes the Assignee, identified below, or its representatives to insert the application number and filing date of the Application when known.

Micron Technology, Inc., a corporation of Delaware having its principal place of business at 8000 S. Federal Way, P.O. Box 6, Boise, Idaho 83707-0006 ("Assignee"), desires to acquire the entire right, title and interest in and to the Invention(s) and the Application, and in and to any patents (collectively, "Patents") that may be granted for the Invention(s) in the United States or in any foreign countries.

For valuable consideration, the receipt and sufficiency of which Assignors acknowledge, Assignors hereby sells, assigns, and transfers to Assignee, its successors, legal representatives and assigns, the entire right, title and interest in and to: the Invention(s), the Application, and any Patents; any divisions, continuations, and continuations-in-part of the Application and any other application claiming priority rights from the Application; any reissues, reexaminations, or extensions of any and all Patents; the right to file foreign applications directly in the name of Assignee; and the right to claim priority rights deriving from the Application (collectively, the "Rights"). Assignor warrants that Assignor owns the Rights, and that the Rights are unencumbered. Assignor also agrees to not sign any writing or do any act conflicting with this assignment, and, without further compensation, sign all documents and do such additional acts as Assignee deems necessary or desirable to: perfect Assignee's

enjoyment of the Rights; conduct proceedings regarding the Rights, including any litigation or interference proceedings; or perfect or defend title to the Rights.

Date: 2015, J. 12

A. Tomohiro
Atsushi Tomohiro

Witness:

Shoko Tomita
Printed Name

Shoko Tomita
Signature

Witness:

Miku Takemasa
Printed Name

Miku Takemasa
Signature